

RJF0412JSP

40 V - 10A - N Channel MOS FET
Power Switching

R07DS1424EJ0100
Rev.1.00
Oct 30, 2018

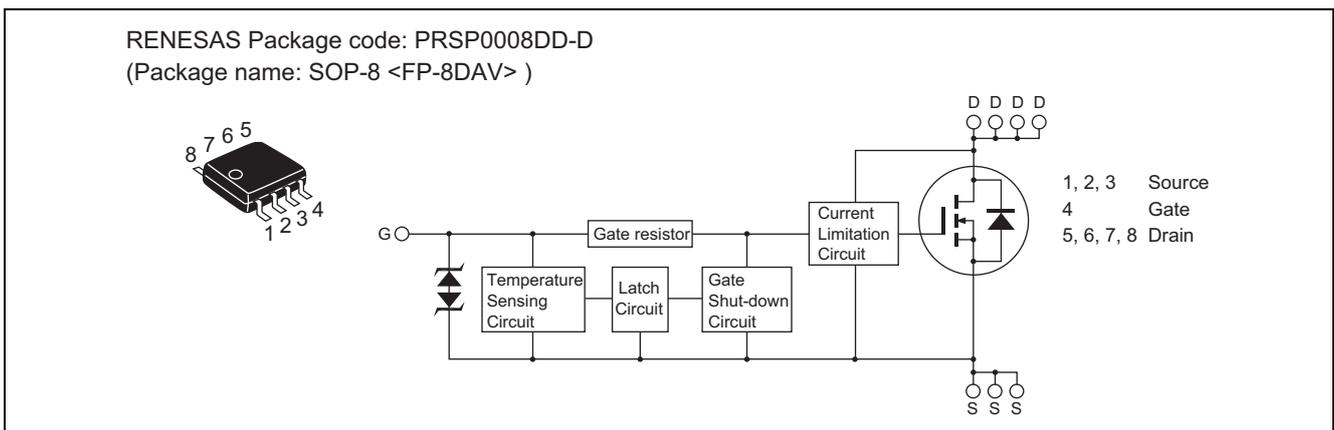
Description

This FET has the over temperature shut-down capability sensing to the junction temperature. This FET has the built-in over temperature shut-down circuit in the gate area. And this circuit operation to shut-down the gate voltage in case of high junction temperature like applying over power consumption, over current etc..

Features

- Logic level operation.
- Built-in the over temperature shut-down circuit.
- High endurance capability against to the short circuit.
- Latch type shut down operation (need 0 voltage recovery).
- Built-in the current limitation circuit.
- High density mounting
- Power supply voltage applies 12 V.
- AEC-Q101 Compliant

Outline



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DSS}	40	V
Gate to source voltage	V_{GSS}	16	V
Gate to source voltage	V_{GSS}	-2.5	V
Drain current	I_D <small>Note 3</small>	10	A
Body-drain diode reverse drain current	I_{DR}	10	A
Avalanche current	I_{AF} <small>Note 2</small>	4.7	A
Avalanche energy	E_{AR} <small>Note 2</small>	147	mJ
Channel dissipation	P_{ch} <small>Note 1</small>	2.5	W
Channel temperature	T_{ch}	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

Notes: 1. When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), $PW \leq 10s$

2. $T_{ch} = 25^\circ C$, $R_g \geq 50 \Omega$

3. It provides by the current limitation lower bound value.

Typical Operation Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Input voltage	V _{IH}	3.5	—	—	V	
	V _{IL}	—	—	1.2	V	
Input current (Gate non shut down)	I _{IH1}	—	—	100	μA	V _i = 8 V, V _{DS} = 0
	I _{IH2}	—	—	50	μA	V _i = 3.5 V, V _{DS} = 0
	I _{IL}	—	—	1	μA	V _i = 1.2 V, V _{DS} = 0
Input current (Gate shut down)	I _{IH(sd)1}	—	0.8	—	mA	V _i = 8 V, V _{DS} = 0
	I _{IH(sd)2}	—	0.35	—	mA	V _i = 3.5 V, V _{DS} = 0
Shut down temperature	T _{sd}	—	175	—	°C	Channel temperature
Gate operation voltage	V _{op}	3.5	—	12	V	
Drain current (Current limitation value)	I _{D limit}	34	—	—	A	V _{GS} = 5 V, V _{DS} = 10 V ^{Note 4}

Note: 4. Pulse test

Electrical Characteristics

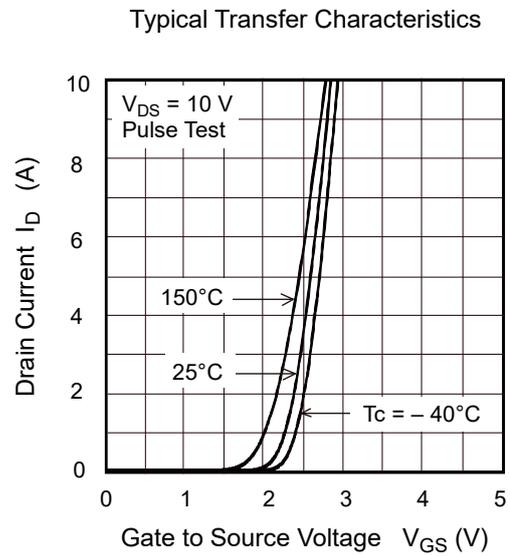
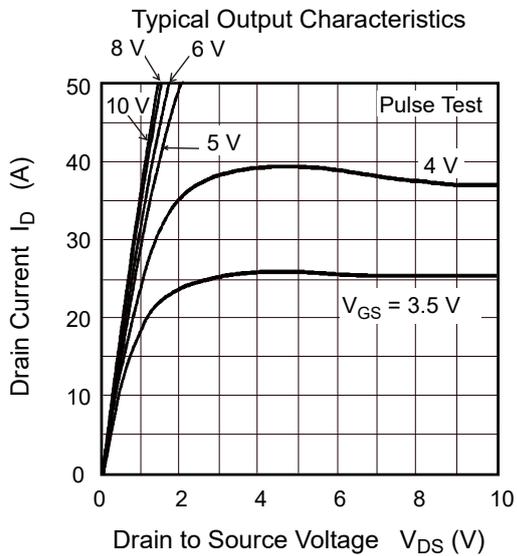
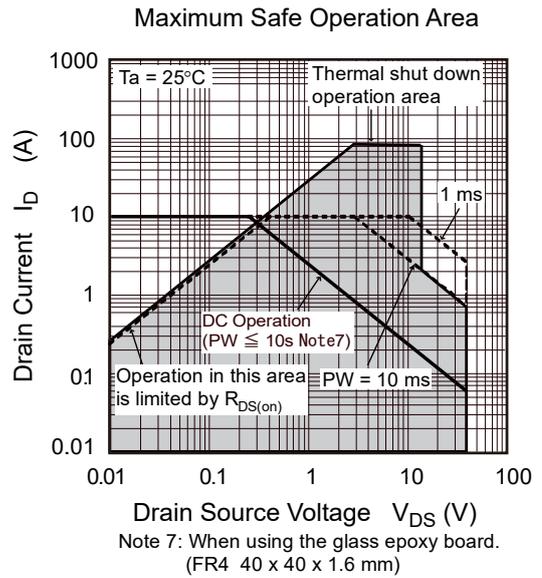
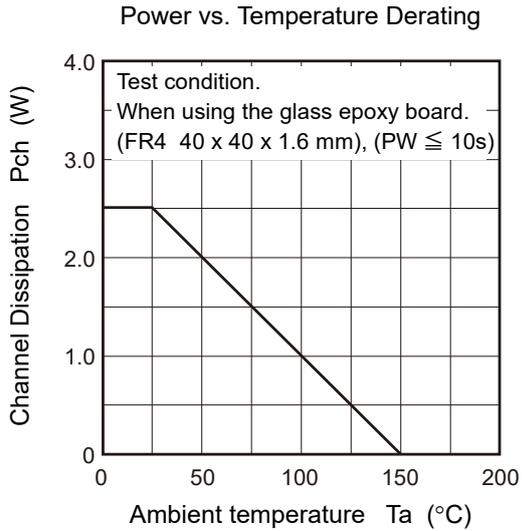
(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain current	I _{D1}	—	—	40	A	V _{GS} = 3.5 V, V _{DS} = 10 V ^{Note 5}
	I _{D2}	—	—	10	mA	V _{GS} = 1.2 V, V _{DS} = 10 V
	I _{D3}	34	—	—	A	V _{GS} = 5 V, V _{DS} = 10 V ^{Note 5}
Drain to source breakdown voltage	V _{(BR)DSS}	40	—	—	V	I _D = 10 mA, V _{GS} = 0
Gate to source breakdown voltage	V _{(BR)GSS}	16	—	—	V	I _G = 800 μA, V _{DS} = 0
	V _{(BR)GSS}	-2.5	—	—	V	I _G = -100 μA, V _{DS} = 0
Gate to source leak current	I _{GSS1}	—	—	100	μA	V _{GS} = 8 V, V _{DS} = 0
	I _{GSS2}	—	—	50	μA	V _{GS} = 3.5 V, V _{DS} = 0
	I _{GSS3}	—	—	1	μA	V _{GS} = 1.2 V, V _{DS} = 0
	I _{GSS4}	—	—	-100	μA	V _{GS} = -2.4 V, V _{DS} = 0
Input current (shut down)	I _{GS(OP)1}	—	0.8	—	mA	V _{GS} = 8 V, V _{DS} = 0
	I _{GS(OP)2}	—	0.35	—	mA	V _{GS} = 3.5 V, V _{DS} = 0
Zero gate voltage drain current	I _{DSS}	—	—	10	μA	V _{DS} = 32 V, V _{GS} = 0, Ta = 125°C
Gate to source cutoff voltage	V _{GS(off)}	1.1	—	2.1	V	V _{DS} = 10 V, I _D = 1 mA
Forward transfer admittance	y _{fs}	10	15	—	S	I _D = 5 A, V _{DS} = 10 V ^{Note 5}
Static drain to source on state resistance	R _{DS(on)}	—	29	43	mΩ	I _D = 5 A, V _{GS} = 5 V ^{Note 5}
	R _{DS(on)}	—	23	37	mΩ	I _D = 5 A, V _{GS} = 10 V ^{Note 5}
Output capacitance	C _{oss}	—	445	—	pF	V _{DS} = 10 V, V _{GS} = 0, f = 1MHz
Turn-on delay time	t _{d(on)}	—	6.5	—	μs	V _{GS} = 5 V, I _D = 5 A, R _L = 6 Ω
Rise time	t _r	—	31.6	—	μs	
Turn-off delay time	t _{d(off)}	—	5.3	—	μs	
Fall time	t _f	—	12.7	—	μs	
Body-drain diode forward voltage	V _{DF}	—	0.85	—	V	I _F = 10 A, V _{GS} = 0
Body-drain diode reverse recovery time	t _{rr}	—	92.5	—	ns	I _F = 10 A, V _{GS} = 0 di _F /dt = 50 A/μs
Over load shut down operation time ^{Note 6}	t _{os1}	—	0.27	—	ms	V _{GS} = 5 V, V _{DD} = 16 V

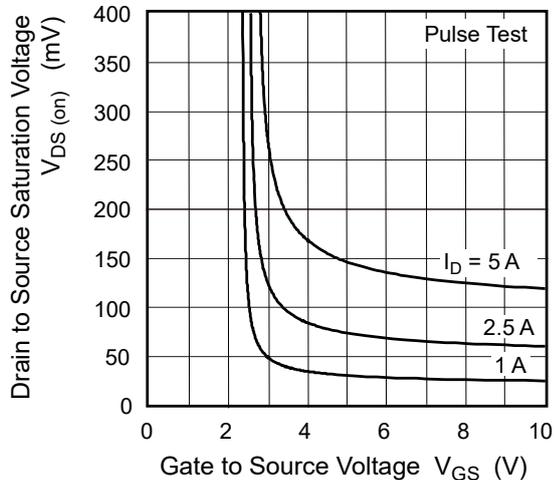
Notes: 5. Pulse test

6. Including the junction temperature rise of the over loaded condition.

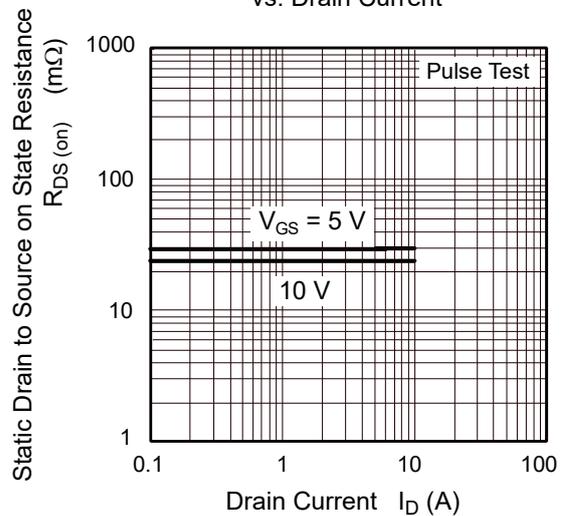
Main Characteristics



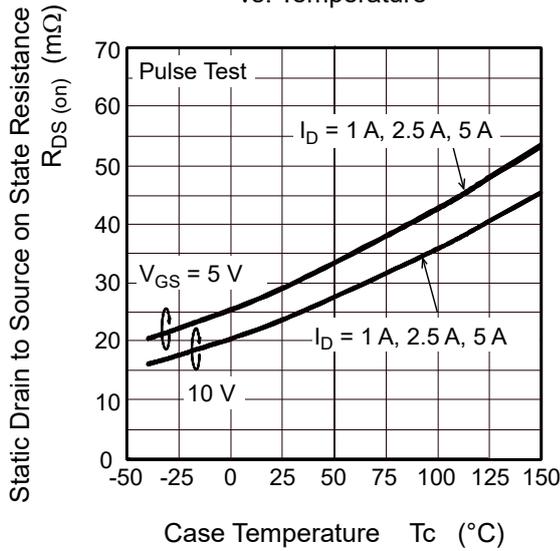
Drain to Source Saturation Voltage vs. Gate to Source Voltage



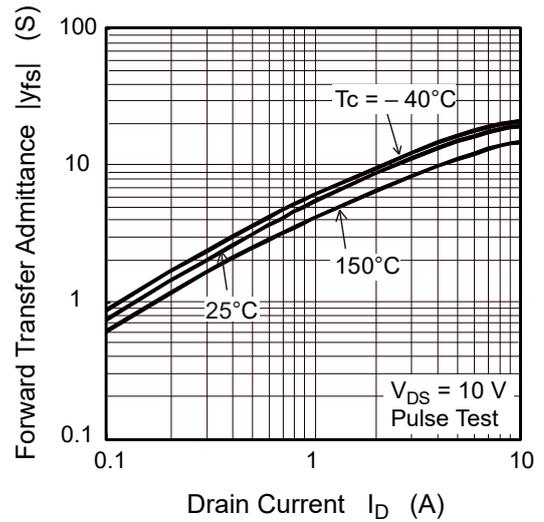
Static Drain to Source on State Resistance vs. Drain Current



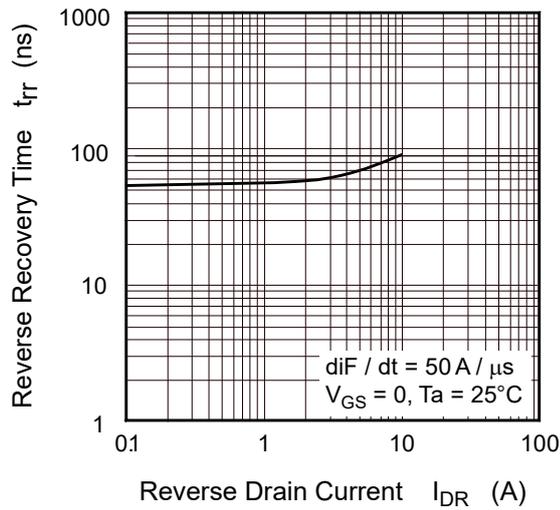
Static Drain to Source on State Resistance vs. Temperature



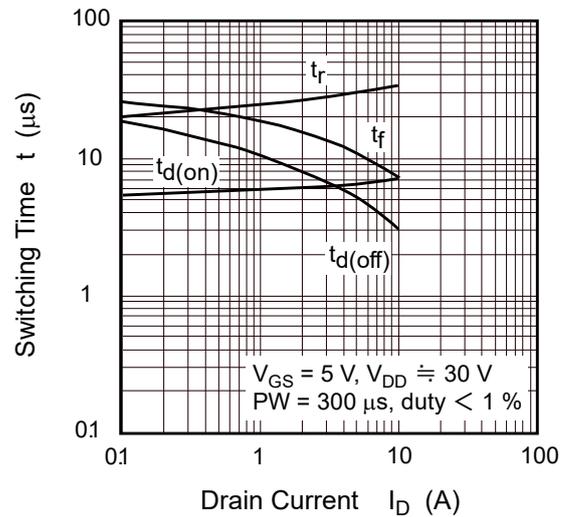
Forward Transfer Admittance vs. Drain Current



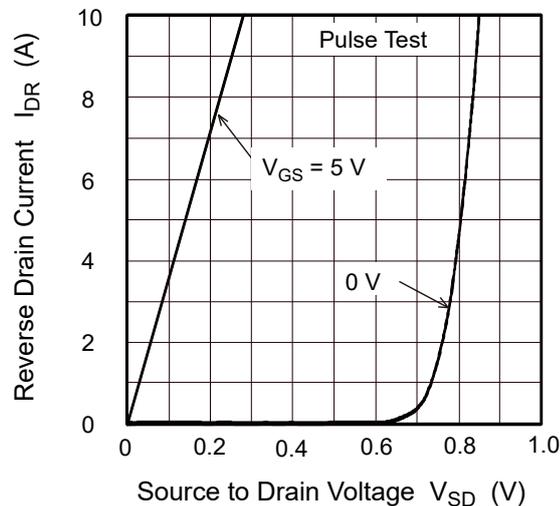
Body-Drain Diode Reverse Recovery Time



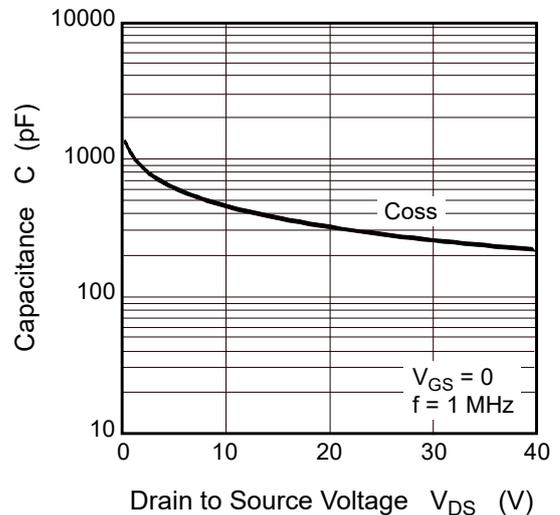
Switching Characteristics



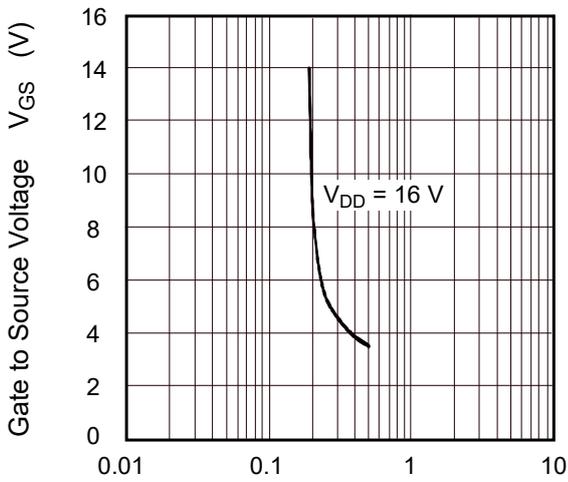
Reverse Drain Current vs. Source to Drain Voltage



Typical Capacitance vs. Drain to Source Voltage

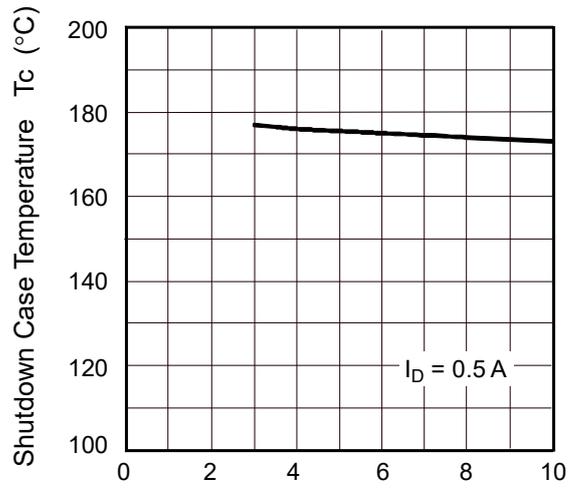


Gate to Source Voltage vs. Shutdown Time of Load-Short Test



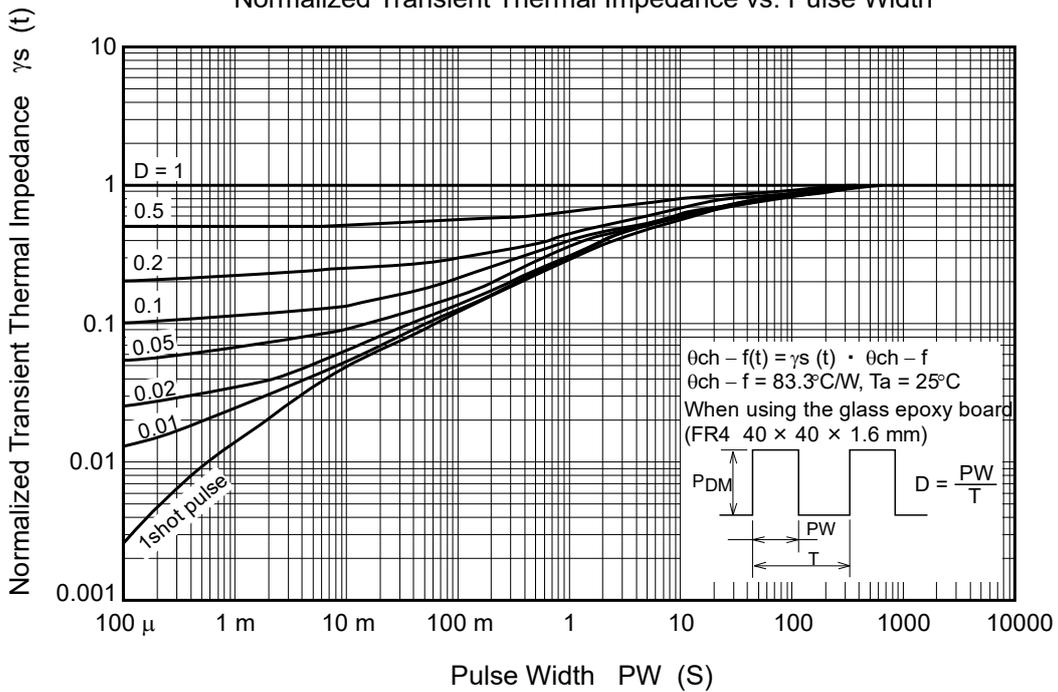
Shutdown Time of Load-Short Test PW (ms)

Shutdown Case Temperature vs. Gate to Source Voltage

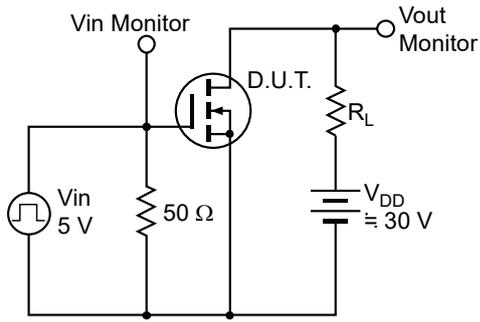


Gate to Source Voltage VGS (V)

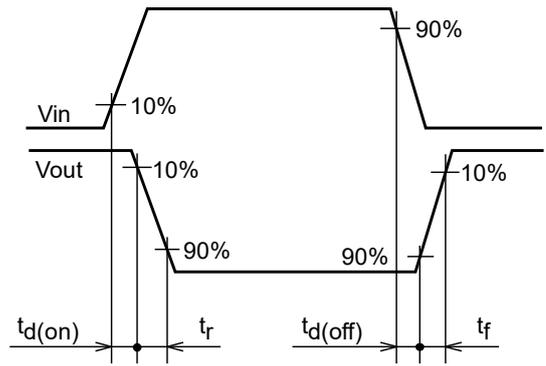
Normalized Transient Thermal Impedance vs. Pulse Width



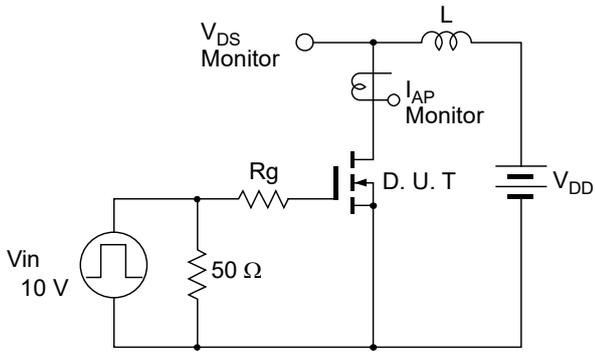
Switching Time Test Circuit



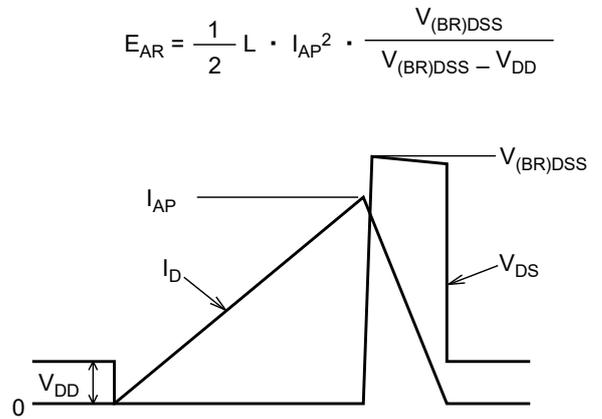
Waveform



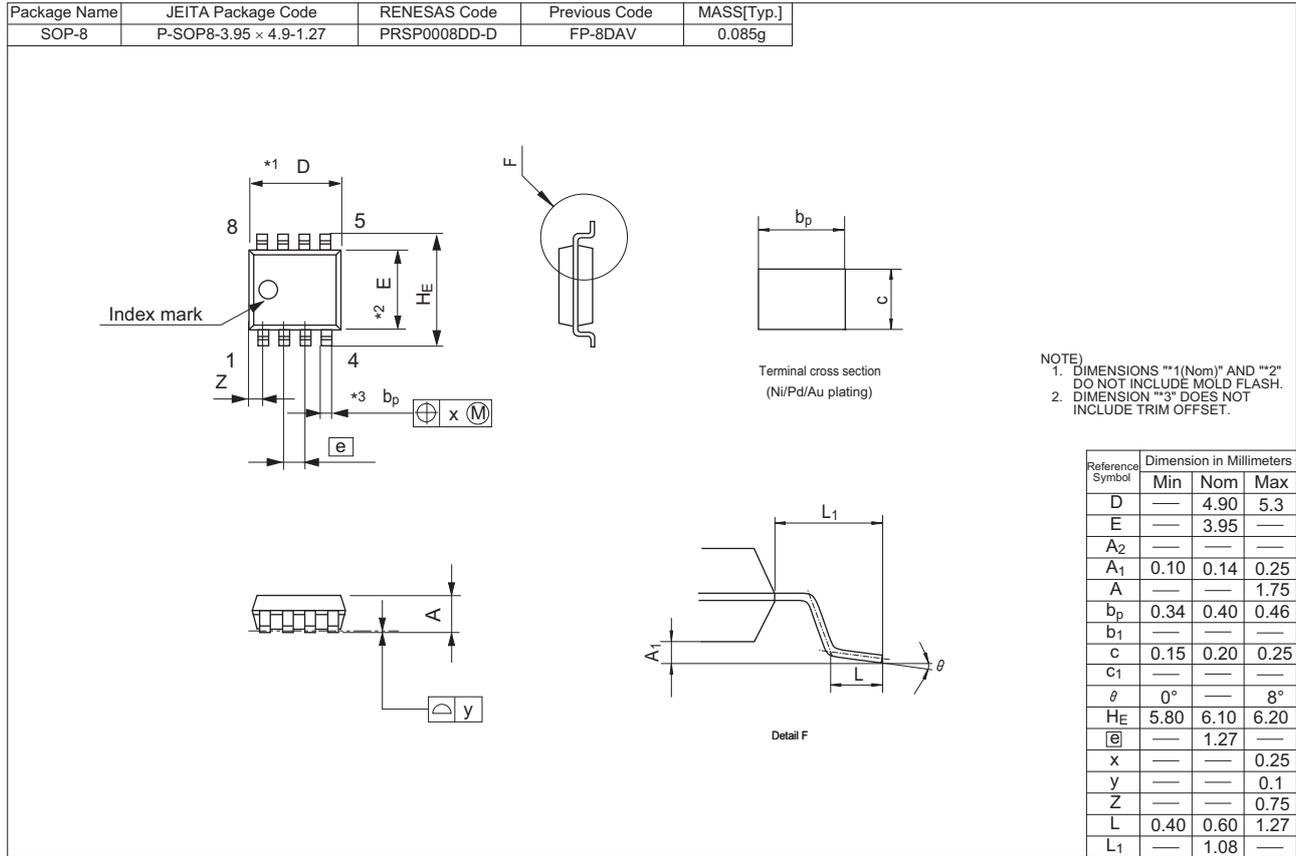
Avalanche Test Circuit



Avalanche Waveform



Package Dimensions



Ordering Information

Orderable Part Number	Quantity	Shipping Container
RJF0412JSP-00-J0	2500 pcs	Taping

Note: The symbol of 2nd "-" is occasionally presented as "#".

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